

# Elizabeth Buitrago, PhD – Resume

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## Education

**PhD Microsystems and Microelectronics**, École Polytechnique Fédérale de Lausanne (EPFL), Switzerland, June 2014.

**MSc Process Engineering**, Eidgenössische Technische Hochschule Zürich (ETHZ), Switzerland, September 2010.

**BSc Chemical Engineering**, University of California San Diego (UCSD), USA, June 2005.

## Experience

### R&D Project leader BiMOS Chips: November 2016 – Present

*ABB Switzerland – Lenzburg (Switzerland)*

- ❖ Development and benchmarking of novel buffer technologies compatible with ultra-thin > 200 mm wafers.
- ❖ Process flow assessment and tool set evaluation (laser anneal) for thin wafer backside processing of IGBTs.
- ❖ Shorted anode process integration enabling  $T_{vj(op)} = 150\text{ }^{\circ}\text{C}$  capability of 6.5kV, 900A IGBT HiPak Module.
- ❖ Project management and process integration of next generation low voltage Trench IGBTs in house and in foundry.
- ❖ Process and device TCAD simulations, device design, electrical characterization and testing of IGBTs. Support of engineering teams within ABB (production, product engineering).

### Postdoctoral Research Scientist & Nanofabrication Lead: July 2014 – October 2016

*Paul Scherrer Institute (PSI) & ASML, X-Ray Interference Lithography Group (XIL-II) – Villigen (Switzerland)*

- ❖ PSI's lead coordinator of international industrial collaboration with ASML and multiple resist vendors worldwide.
- ❖ Process optimization and characterization of state-of-the-art chemically amplified (CAR) and inorganic resist and materials for extreme ultraviolet (EUV) lithography at the Swiss Light Synchrotron Source (SLS).
- ❖ 10 nm half-pitch resolution achieved with CAR via ASML collaboration.
- ❖ Nanofabrication lead in the development of highly efficient diffraction gratings (masks) with novel materials for interference lithography (IL) at the Lab of Micro and Nanotechnology (LMN) in PSI.

### Research Engineer (PhD Thesis): Oct. 2010 – June 2014

*EPFL, Nanoelectronic Devices Laboratory (Nanolab) – Lausanne (Switzerland): Prof. A. M. Ionescu*

- ❖ 3D vertically stacked silicon nanowire (SiNW) field effect transistor (FET) realized as a proof-of-concept device for its future implementation into low cost biosensors.
- ❖ Led multi-institution collaboration within two European projects resulting in successful microfluidic platform development, electrical characterization and surface functionalization for ultra-low concentration protein sensing.
- ❖ Research on high performance SiNW/Fin based FETs for biosensing (junctionless and enhancement mode).
- ❖ Careful design and fabrication of CMOS compatible process flow for robust 3D heterogeneous systems integration.
- ❖ 3D TCAD-Sentaurus process and device simulations, teaching and supervision of master students.

### Process Engineer (Wet Process): Sept. 2007- Oct.2008

*Micron Technology (300 mm Wafer Fab) – Manassas, VA (USA)*

- ❖ Direct and sustain process improvements using statistical process control (SPC).
- ❖ Strategically identify and analyze process failures. Audit process recipes, configure hardware and implementation of process enhancements.
- ❖ Identifying, understanding, and resolving defect issues, assisting area technicians troubleshooting problems, improving preventative maintenance procedures, and optimizing overall tool performance.

### Primary Process Engineer (Metal Deposition): Jan. 2006 – Jan. 2007

*AMI Semiconductor (On Semiconductor) – Pocatello, ID (USA)*

- ❖ Worked directly with production and engineering teams to review existing procedures and identify and implement cost, quality and productivity improvements.
- ❖ Statistical analysis, design of experiments (DOE), SPC and process capability studies. Responsibilities included sustaining, data analysis, continuous improvement of current procedures, cost savings, new process introduction.

## Skills, Honors & Activities

- ❖ Bilingual (Spanish, English), basic French and German (A2).
- ❖ Triton Engineering Council Representative AICHE (2003 – 2005). IEEE member (2010 - present).
- ❖ Donald F. Othmer Sophomore Academic Excellence Award (AICHE).